



# Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

Adobe Reader version 7.0.5 is required to complete this declaration.

1752-2 1.1	IPC Web Site for Information on IPC-1752 Standard <a href="http://www.ipc.org/IPC-175x">http://www.ipc.org/IPC-175x</a>	Form Type * Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informat
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## Supplier Information

Company Name * <b>SEMTECH CORP. (CPMGR01)</b>	Company Unique ID	Unique ID Authority	Response Date * <b>2012-01-07</b>	Response Document ID				
Contact Name * <b>ROYA READER</b>	Title - Contact Quality Customer Service Spec	Phone - Contact * <b>805-389-2742</b>	Email - Contact * <b>Rreader@semtech.com</b>	Duplicate Contact -> Authorized Representative				
Authorized Representative * <b>ROYA READER</b>	Title - Representative Quality Customer Service Spec	Phone - Representative * <b>805-389-2742</b>	Email - Representative * <b>Rreader@semtech.com</b>	Supplier Comments or URL for Additional Information				
Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight *	UOM	Unit Type
SX8651ICSTRT	SX8651ICSTRT					0.00354741	mg	Each
Alternate Recommendation				Alternate Item Comments				

## Manufacturing Process Information

Terminal Plating / Grid Array Material <b>Tin/Silver/Copper (Sn/Ag/Cu)</b>	Terminal Base Alloy <b>Other</b>	J-STD-020 MSL Rating <b>1</b>	Peak Process Body Temperature <b>375 C</b>	Max Time at Peak Temperature <b>3.6 seconds</b>	Number of Reflow Cycles <b>1</b>
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Comments  
**Terminal Base Alloy:TiW/Cu, Cu/Ni**

Save the fields in this form to a file

Export Data

Import fields from a file into this form

Import Data

Clear all of the fields on this form

Reset Form

Lock the fields on this form to prevent changes

Lock Supplier Fields

## RoHS Material Composition Declaration

Declaration Type \*

Detailed

**RoHS Directive 2002/95/EC** **RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2002/95/EC and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.

RoHS Declaration \*

3 - Item(s) does not contain RoHS restricted substances per the definition above except for lead in solders and selected exemptions, if any

Supplier Acceptance \*

Accepted

**Exemptions:** If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version

EL-2006/690/EC

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## Declaration Signature

**Instructions:** Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

## Homogeneous Material Composition Declaration for Electronic Products

**SubItem Instructions:** The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

**Substance Instructions:** [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

**Line Functions:** +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

+I	-I	Item/SubItem Name	+M	-M	Homogeneous Material	Weight	Unit of Measure	+C	-C	Level	Substance Category	+S	-S	Substance	CAS	Exempt	Weight	Unit of Measure	Tolerance		PPM
																			-	+	
		Solder Bump			Die	0.001950	mg			Supplier	Die			Si			0.001950	mg			549,75
					HD4100	0.000024	mg			Supplier	PI			Methanol	67-56-1		0.000000	mg	1	5	205
														N-Methyl-2-Prollidone			0.000009	mg	30	60	2,805
														MethacrylateMonomer			0.000001	mg	5	10	479
														PhotosensitivePolyimid			0.000010	mg	30	60	2,873
														ProprietaryIngredient(s)			0.000001	mg	5	10	479
					TiW Target	0.000000	mg			Supplier	Seed metal(RDL)			Ti	7440-32-6		0.000000	mg		10	27
														W	7440-33-7		0.000000	mg	90		242
					Cu Solution	0.000027	mg			Supplier	RDL			Cu	7440-50-8		0.000027	mg		100	7,740
					TiW Target	0.000000	mg			Supplier	Seed metal(UBM)			Ti	7440-32-6		0.000000	mg		10	27
														W	7440-33-7		0.000000	mg	90		242
					Cu Solution	0.000027	mg			Supplier	UBM			Cu	7440-50-8		0.000027	mg		100	7,740
					Ni Solution	0.000010	mg			B	Nickel (external applic			Nickel	7440-02-0		0.000010	mg		100	3,058
					SAC266	0.001246	mg			Supplier	Solder Ball			Sn	7440-31-5		0.001206	mg		96.8	340,09
														Ag	7440-22-4		0.000032	mg		2.6	9,135
														Cu	7440-50-8		0.000007	mg		0.6	2,108
					LC2850	0.000258	mg			Supplier	BSP			Silica			0.000144	mg	32	79	40,655
														Epoxy resin			0.000055	mg	10	32	15,545
														Acrylic resin			0.000055	mg	10	32	15,545
														Carbon black	1333-86-4		0.000004	mg		3	1,196